

PRELIMINARY AMENDMENT

Serial Number: 10/023,720

Filing Date: December 21, 2001

Title: DEVICE AND METHOD FOR PACKAGE WARP COMPENSATION IN AN INTEGRATED HEAT SPREADER

Assignee: Intel Corporation

Page 2

Dkt: 884.A12US1 (INTEL)

IN THE ABSTRACT OF THE DISCLOSURE

Please amend the Abstract as follows:

A device and method for designing and manufacturing an integrated heat spreader so that the integrated heat spreader will have a flat surface on which to mount a heat sink after being assembled into a package and exposed to the heat of a die. This device and method for designing and manufacturing an integrated heat spreader would generate a heat spreader that would be built to compensate for deformations resulting from (1) physical manipulation during assembly (2) thermal gradients during operation and (3) differing rates of expansion and contraction of the package materials coupled with multiple package assembly steps at elevated temperatures so that one surface of the integrated heat spreader would have a flat shape.